

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
LANG CHENG	01/21/2020
RECEIVING PARTY DATA	
Name:	GUANGDONG CHIPPACKING TECHNOLOGY CO., LTD.
Street Address:	QIPAI BUILDING, QIPAI TECHNOLOGY ROAD, SHIPAI TOWN, DONGGUAN
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State/Country:	CHINA
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	29721386
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ATTORNEY DOCKET NUMBER:	KC34363
NAME OF SUBMITTER:	LANG CHENG
SIGNATURE:	/Lang CHENG/
DATE SIGNED:	01/21/2020
Total Attachments: 2	
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转让合同

鉴于，我/我们，程浪，地址为 广东省东莞市石排镇气派科技路气派大厦（下文简称为《申请人》），就集成电路封装体（QFL8-28）发明了一项新的外观设计（下文简称为《所述外观设计》），并在 2020 年 1 月 21 日就所述外观设计提交了美国专利申请（下文简称为《所述申请》），且

鉴于，广东气派科技有限公司，地址为中国广东省东莞市石排镇气派科技路气派大厦（下文简称为《受让人》），邮寄地址为中国广东省东莞市石排镇气派科技路气派大厦，希望获得所述申请的所有权利、产权及利益；

因此，我/我们作为所述申请的申请人，现以 1 美元作为代价（并特此告知收到收条），特此出售、转让及让予上述受让人所述外观设计在美国的所有专属权利，以及就所述外观设计在美国所有可能授予的专利的权利、产权及利益。我/我们现授权并请求美国专利及商标局局长授予受让人所述外观设计在美国专利及其所有权利、产权及利益，供受让人及其法定代表使用，直至可能授予的专利权期限，该等权利与我/我们在本转让合同没有订立的情况下所持有的权利完全相同）。

本合同在 2020 年 1 月 21 日签订。

转让人签署	
转让人姓名	程浪
受让人签署	
受让人代表姓名	梁大钟
受让人代表职务	法人代表



ASSIGNMENT DEED

Whereas, I/We, Lang CHENG of Qipai Building, Qipai Technology Road, Shipai Town, Dongguan, Guangdong, China, hereafter referred to as applicant, have invented a new design in respect of an Integrated circuit package for which an application for a United States Design Patent was filed on 21 January 2020, and

Whereas, Guangdong Chippacking Technology Co., Ltd. of Qipai Building, Qipai Technology Road, Shipai Town, Dongguan, Guangdong, China here referred to "assignee" whose mailing address is Qipai Building, Qipai Technology Road, Shipai Town, Dongguan, Guangdong, China is desirous of acquiring the entire right, title and interest in the same;

Now, therefore, in consideration of the sum of US\$ 1, the receipt whereof is other good and valuable consideration, I/We, the applicant(s), by these presents do sell, assign and transfer unto said assignee the full and exclusive right to the said design in the United States and the entire rights, title and interest in and to any and all Patents which may be granted therefore in the United States. I/We hereby authorize and request the Director of the U.S. Patent and Trademark Office to issue said United States Patent to said assignee, of the entire right, title, and interest in and to the same, for his sole use and behoof; and for the use and behoof of his legal representatives, to the full end of the term for which said Patent may be granted, as fully and entirely as the same would have been held by me had this assignment and sale not been made.

Executed this 21st day of January, 2020.

Signature of Assignor	
Name of Assignor	Lang CHENG
Signature of Assignee	
Name of Assignee's signatory	Dazhong LIANG
Title of Assignee's signatory	Legal Representative